

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Normally – OFF Silicon Carbide Super Junction Transistor

V _{DS}	=	1200 V
$V_{DS(ON)}$	=	1.4 V
I _D	=	50 A
R _{DS(ON)}	=	28 mΩ

Features

- 175 °C maximum operating temperature
- Temperature independent switching performance
- Gate oxide free SiC switch
- Suitable for connecting an anti-parallel diode
- · Positive temperature coefficient for easy paralleling
- · Low gate charge
- · Low intrinsic capacitance

Package

RoHS Compliant





TO-247AB

Advantages

- · Low switching losses
- Higher efficiency
- High temperature operation
- · High short circuit withstand capability

Applications

- Down Hole Oil Drilling, Geothermal Instrumentation
- Hybrid Electric Vehicles (HEV)
- Solar Inverters
- Switched-Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Induction Heating
- Uninterruptible Power Supply (UPS)
- Motor Drives

Maximum Ratings unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Drain – Source Voltage	V _{DS}	V _{GS} = 0 V	1200	V
Continuous Drain Current	I _D	T _{C,MAX} = 95 °C	50	Α
Gate Peak Current	I _{GM}		10	Α
Reverse Gate – Source Voltage	V_{SG}		25	V
Reverse Drain – Source Voltage	$V_{ exttt{SD}}$		25	V
Power Dissipation	P _{tot}	T _C = 25 °C	5	W
Storage Temperature	T _{stg}		-55 to 175	°C

Electrical Characteristics at T_i = 175 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values		I I m i 4	
		Conditions -	min.	typ.	max.	Unit
On Characteristics						
		I _D = 50 A, I _G = 1000 mA, T _j = 25 °C		1.4		
Drain – Source On Voltage	$V_{DS(ON)}$	I_D = 50 A, I_G = 2000 mA, T_j = 125 °C		1.6		V
		I_D = 50 A, I_G = 4000 mA, T_j = 175 °C		2.2		
		$I_D = 50 \text{ A}, I_G = 1000 \text{ mA}, T_j = 25 ^{\circ}\text{C}$		28		
Drain – Source On Resistance	$R_{DS(ON)}$	I_D = 50 A, I_G = 2000 mA, T_j = 125 °C		32		mΩ
	-(-,	$I_D = 50 \text{ A}, I_G = 4000 \text{ mA}, T_j = 175 °C$		44		
Cata Farward Valtage	\/	$I_G = 500 \text{ mA}, T_j = 25 \text{ °C}$		3.3		V
Gate Forward Voltage	$V_{GS(FWD)}$	$I_G = 500 \text{ mA}, T_j = 175 ^{\circ}\text{C}$		3.1		V
DC Current Gain	β	$V_{DS} = 5 \text{ V}, I_{D} = 50 \text{ A}, T_{i} = 25 ^{\circ}\text{C}$		TBD		
		$V_{DS} = 5 \text{ V}, I_D = 50 \text{ A}, T_j = 175 °C$		TBD		
Off Characteristics						
		$V_R = 1200 \text{ V}, V_{GS} = 0 \text{ V}, T_i = 25 ^{\circ}\text{C}$		18		
Drain Leakage Current	I _{DSS}	$V_R = 1200 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 125 \text{ °C}$		26		μA
		$V_R = 1200 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 175 ^{\circ}\text{C}$		35		



Electrical Characteristics at T_j = 175 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values		11::4	
			min.	typ.	max.	Unit
Switching Characteristics						
Turn On Delay Time	$t_{d(on)}$			tbd		ns
Rise Time	t _r	$V_{DD} = 800 \text{ V}, I_D = 50 \text{ A},$		tbd		ns
Turn Off Delay Time	$t_{\sf d(off)}$	$R_{G(on)} = R_{G(off)} = 44 \Omega,$ $V_{GS} = -8/15 \text{ V, L} = 1.1 \text{ mH,}$		tbd		ns
Fall Time	t _f	FWD = GB50SLT12,		tbd		ns
Turn-On Energy Per Pulse	E _{on}	T _j = 25 °C		tbd		μJ
Turn-Off Energy Per Pulse	E _{off}	Refer to Figure 11 for gate current waveform		tbd		μJ
Total Switching Energy	E _{ts}			tbd		μJ
Turn On Delay Time	t _{d(on)}			tbd		
Rise Time	t _r	$V_{DD} = 800 \text{ V, } I_{D} = 50 \text{ A,}$ $R_{G(on)} = R_{G(off)} = 44 \Omega,$ $V_{GS} = -8/15 \text{ V, } L = 1.1 \text{ mH,}$		tbd		ns
Turn Off Delay Time	$t_{d(off)}$			tbd		ns
Fall Time	t _f	FWD = GB50SLT12.		tbd		ns
Turn-On Energy Per Pulse	E _{on}	T _j = 175 °C Refer to Figure 11 for gate current waveform		tbd		μJ
Turn-Off Energy Per Pulse	E _{off}			tbd		μJ
Total Switching Energy	E _{ts}			tbd		μJ
Thermal Characteristics						
Thermal resistance, junction - case	R_{thJC}			1.64		°C/W

TBD TBD

Figure 1: Typical Output Characteristics at 25 °C

Figure 2: Typical Output Characteristics at 125 °C



TBD

TBD

Figure 3: Typical Output Characteristics at 175 °C

Figure 4: Typical Gate Source I-V Characteristics vs.
Temperature

TBD

TBD

Figure 5: Normalized On-Resistance and Current Gain vs. Temperature

Figure 6: Typical Blocking Characteristics

TBD

TBD



TBD TBD

Figure 9: Typical Turn On Energy Losses and Switching Times vs. Temperature

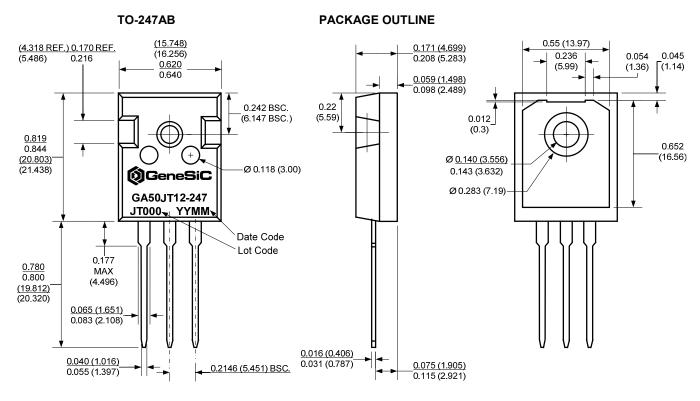
Figure 10: Typical Turn Off Energy Losses and Switching Times vs. Temperature

TBD

Figure 11: Typical Gate Current Waveform



Package Dimensions:



NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

Revision History					
Date	Revision	Comments	Supersedes		
2013/01/14	0	Initial release			

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